ASSOCIATION CONNECTED ELECTRONICS INDUST	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ıs Materia	als and Mf	g Informa	tion		
Supplier Info	rmation															
Company name*			Company un	Company unique ID			Unique ID Authority					Response Date*				
nsemi													2025-07-15			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*					
Product-Env-Ste	ewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorized Repr	esentative*	Title - Repre	Title - Representative			Phone - Representative*					Email - Representative*					
Product-Env-Ste	ewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Reque	quester Item Number Mfr Iter		m Number Mfr Item Name				Effective Date	ate Version Manufactu		/Ianufacturing	g Site	W	eight*	UOM	Unit Type	
		LM324ADTBR2G ANA LC		ANA LO PWR (NA LO PWR OP AMP QUAD		2025-07-15 PH		PH1		5	51.764 mg		Each		
Ianufacturin	ng Proccess Informa	tion														
Termin	al Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MS	0-020 MSL Rating		Peak Process Body Temperatu		re Max Time at Peak Temper		Temperatu	ature Number of Reflow Cycles		cles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С	30		second	s 3			
Comments																
vel 1 - maximur	n time at peak temperatu	re during so	ldering is 10-3	30 seconds												
or more inform	ation regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.476	mg	Supplier	Silicon (Si)	7440-21-3		1.476	mg
Die Attach	0.191	mg		Epoxy resin	proprietary data		0.0439	mg
			Supplier	Silver (Ag)	7440-22-4		0.1471	mg
Lead Frame	14.903	mg	Supplier	Silver (Ag)	7440-22-4		0.6796	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0209	mg
			Supplier	Silicon (Si)	7440-21-3		0.0924	mg
			В	Nickel (Ni)	7440-02-0		0.4262	mg
			Supplier	Copper (Cu)	7440-50-8		13.6839	mg
Mold Compound-Black	34.856	mg		Epoxy resin	proprietary data		1.7428	mg
			Supplier	Phenol Resin	Proprietary Data		1.3942	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.4856	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3486	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		27.8848	mg
Plating	0.239	mg	Supplier	Tin (Sn)	7440-31-5		0.239	mg
Wire Bond	0.099	mg	Supplier	Palladium (Pd)	7440-05-3		0.002	mg
			Supplier	Copper (Cu)	7440-50-8		0.097	mg